



02-12-2009

PATENT

IN THE UNITED STATES



DEMARK OFFICE

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Please record the attached assignment document.

1. Name of conveying parties: Rikiya KATO  
Sakie YAMAGATA
2. Name and address of receiving party: Senju Metal Industry Co., Ltd.  
23 Senju-Hashido-cho,  
Adachi-ku,  
Tokyo 120-8555, Japan
3. Nature of conveyance: Assignment  
Execution date of assignment: December 16, 2008
4. U.S. Application No.: 12/226,653  
International filing date: April 23, 2007
5. Name and address of party to whom correspondence concerning the attached document should be mailed:

Michael Tobias  
1629 K Street N.W., Suite 300  
Washington, D.C. 20006  
Tel: (301) 571-0052

02/11/2009 NJAMA1 00000002 12226653  
01 FC:8021 40.00 UP

6. Total number of applications involved: 1

7. Total fee: \$40.00  
[X] Enclosed  
[ ] Authorized to be charged to the deposit account  
[X] The Commissioner is authorized to charge any  
deficiencies in the fee payment accompanying this  
communication and to credit any excess payment of fees  
to Deposit Account No. 50-1079.

8. Statement and signature

To the best of my knowledge and belief, the foregoing  
information is true and correct and any attached copy is a  
true copy of the original document.

February 9, 2008  
Date

*Michael Tobias*  
Michael Tobias  
Registration No. 32,948  
Customer No. 27649

Total number of pages comprising cover  
sheet, attachments and document: 4

## ASSIGNMENT

WHEREAS, We, **Rikiya KATO** and **Sakie YAMAGATA**, residing in 5-4-4, Benten, Soka-shi, Saitama 340-0004 Japan; and 1-20-1, Yanagihara, Adachi-ku, Tokyo 120-0022 Japan; respectively, have invented certain new and useful improvements entitled

### SOLDER PASTE

(a) for which an application for United States Letters Patent was filed on  
October 24, 2008

and identified by United States Serial No. 12/226,653;  
or

(b) for which an application for United States Letters Patent was executed on  
\_\_\_\_\_

AND, WHEREAS, **SENJU METAL INDUSTRY CO., LTD.**, a corporation of Japan, having a place of business at **23 Senju-Hashido-cho, Adachi-ku, Tokyo 120-8555, Japan**, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, for good and valuable consideration paid to us by said assignee, the receipt of which is hereby acknowledged, we do hereby assign, sell, transfer, and set over unto said assignee the entire right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals, and/or extensions thereof, said assignee to have and to hold the interests herein assigned to the full ends of the terms of said Letters Patent and any and all divisions, reissues, continuations, continuations-in-part, renewals, and/or extensions thereof, respectively, as fully and entirely as the same would have been held and enjoyed by us had this assignment not been made.

The Commissioner for Patents is requested to issue such Letters Patent in accordance herewith. We covenant that we are the lawful owners of the said application, inventions, and improvements, that the same are unencumbered, that no license has been granted to make, use, or vend the said inventions or improvements or any of them, and that we have the full right to make this assignment.

And for the consideration aforesaid, we agree jointly and individually that we will communicate to said assignee or the representatives thereof any facts known to us respecting said inventions and improvements, and will, upon request, but without expense to us, testify in any legal proceedings, sign all lawful papers, execute all

divisional, reissue, continuation, continuations-in-part, renewal, and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts, deemed necessary or expedient by said assignee or by counsel for said assignee, to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This assignment shall be binding upon our heirs, executors, administrators, and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors, and/or assigns, as the case may be, of said assignee.

We authorize the assignee and its agents to insert or to have inserted in this instrument the execution date/or the filing date and serial number of our patent application.

Dated: December 16, 2008

Rikiya Kato  
Rikiya KATO

Dated: 16 Dec, 2008

Sakie Yamagata  
Sakie YAMAGATA